L	Hits	Search Text	DB	Time stamp
Number				
1	9693	324/754-765.ccls.	USPAT;	2004/06/12
			US-PGPUB;	09:13
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
2	391	(electrode adj1 pad) and (wiring adj	USPAT;	2004/06/12
		board) and bonded	US-PGPUB;	09:15
		20020, 0000000	EPO; JPO;	
			DERWENT;	
			IBM TDB	
3	18	324/754-765.ccls. and ((electrode adj1	USPAT;	2004/06/12
		pad) and (wiring adj board) and bonded)	US-PGPUB;	09:15
		pad, and (willing ad) bould, and bonded,	EPO; JPO;	
			DERWENT;	
			IBM TDB	
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